

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4444774

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HYUN KYU KIM	05/23/2017
MI YEON LEE	05/23/2017
JEONG JU MOON	05/23/2017
JOO HO KIM	05/23/2017
SEOK HO JEONG	05/23/2017
RECEIVING PARTY DATA	
Name:	LG CHEM, LTD.
Street Address:	128, YEOUI-DAERO, YEONGDEUNGPO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	07336
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15533264
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	29137.02376.US00
NAME OF SUBMITTER:	MATTHEW T. BAILEY
SIGNATURE:	/Matthew T. Bailey/
DATE SIGNED:	06/05/2017
Total Attachments: 2	
source=Assignment#page1.tif	

Assignment of Application

WHEREAS, I (WE)	KIM, Hyun Kyu; LEE, Mi Yeon; MOON, Jeong Ju; KIM, Joo Ho; JEONG, Seok Ho		
			, respectively,
have invented certain new and useful improvements in:			
PLASTICIZER COMPOSITION, RESIN COMPOSITION AND METHOD FOR PREPARING THEREOF			
for which an application for Letters Patent was executed on			

(Application No.		, Filed), and
WHEREAS,	LG CHEM, LTD.			
(hereinafter referred to as "ASSIGNEE") having a place of business at: 128, Yeoui-daero, Yeongdeungpo-gu, Seoul 07336, Republic of Korea				

is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), and for other good and valuable consideration, the receipt whereof is hereby acknowledged, I (WE), by these presents hereby agree to sell, assign and transfer unto said ASSIGNEE, and ASSIGNEE'S heirs, successors, and assigns, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, substitute, and reissue applications, and all Letters Patent, extensions, reissues, and reexamination certificates which may be granted therefore in the United States and its territorial possessions and in any and all foreign countries.

I (WE) hereby authorize and request the Patent Office Officials in the United States and Its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behalf of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

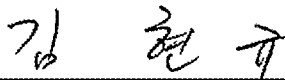
Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and perform all affirmative acts which may be necessary in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said




ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Dentons US LLP, Attorneys at Law, 1900 K Street, N.W., Washington, D.C. 20006 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

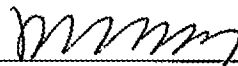
Date: May 23, 2017


(Signature of Inventor)
KIM, Hyun Kyu

Date: May 23, 2017


(Signature of Inventor)
LEE, Mi Yeon


Date: May 23, 2017


(Signature of Inventor)
MOON, Jeong Ju

Date: May 23, 2017


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KIM, Joo Ho

Date: May 23, 2017


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